



# Electronic

# BALVER ZINN®

## Technical Data Sheet

### BALVER ZINN SOLDERPASTE

### RMA H-1 FDQ SN97C

### (SnAg3.0Cu0.5)

#### General information

**BALVER ZINN SOLDERPASTE RMA H-1 FDQ SN97C** is a lead-free, solder paste containing silver, based on SnAg3.0Cu0.5 with a melting range 217-219°C. **BALVER ZINN SOLDERPASTE RMA H-1 FDQ SN97C** can be used for air or nitrogen reflow applications and gives excellent print and reflow characteristics. The post soldering residues of **BALVER ZINN SOLDERPASTE RMA H-1 FDQ SN97C** are very low and concentrated around the pad. **BALVER ZINN SOLDERPASTE RMA H-1 FDQ SN97C** is a no clean formulation. The residues can remain on the board after reflow and will not interfere with in-circuit test. The paste flux compositions allows reflow profiles with a peak temperature of 235°C - 250°C and enable a wide process window with lead free solders. We recommend a temperature of 230°C or 240°C for vapour phase soldering.

\***BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN97C** does not contain hazardous substances beyond the limits prescribed by EU Directive 2011/65/EU ("RoHS II").

Technical information and further Technical Data Sheets can be found on our website ([www.BALVERZINN.com](http://www.BALVERZINN.com)). You can also obtain all information and documents directly from **BALVER ZINN**.

#### BALVER ZINN Production Programme

- The **BALVER ZINN** production programme also includes solder pastes, flux and solder wires. Beside the **SN100C®** product family, **BALVER ZINN** offers additional unpatented and patented solder alloys for wave soldering, reflow and rework.

#### Product Properties

- Flux classified according to J-STD-004 as: **ROL1**
- Paste classified according to EN 61190 -1-2: **ROL1**
- RoHS compliant\*
- Compatible with RoHS conform solder masks
- Bright and shiny solder joints with SN100C®
- Long tack time.
- Excellent print results with 16 and 20 mils pitch.

#### Physical and Chemical Properties of flux RMA H-1 FDQ

<b>Metal content:</b>	87.5 %
<b>Viscosity:</b> Brookfield viscometer @ 10 rpm and 25°C	330 Pas
<b>Initial Tackiness:</b> J-STD-004, IPC-TM-650, Method 2.4.44	100 gf
<b>Slump Test:</b> JIS-Z-3284 Appendix 7; Appendix 8	pass
<b>Solder Ball Test:</b> JIS-Z-3284 Appendix 11	pass
<b>Wetting Test:</b> JIS-Z-3284 Appendix 10	pass
<b>Copper Plate Corrosion:</b> JIS-Z-3197 6.6.1	pass
<b>SIR, IPC:</b> J-STD-004, IPC-TM-650, Methode 2.6.3.3	pass

**Standard application:**  
87.5 % Metal for dispensing

**BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN 97C** is available in SN97C (SnAg3.0Cu0.5) lead free alloys. Type 3 powder from 45-20 micron for fine pitch applications.

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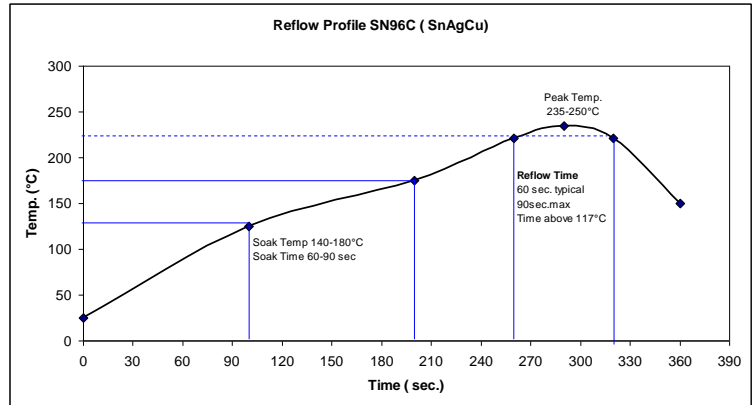
#### RMA H-1 FDQ SN97C

#### (SnAg3.0Cu0.5)

BALVER ZINN<sup>®</sup>

**Recommended Reflow Profile:**

The recommended reflow profile for **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN97C** offers a wide process window allowing adjustment to suit component board loadings. The illustrated profile is based on a full convection reflow system.



**Printing Parameters:**

DEK ProFlow and MPM Pumphead approved

- |                      |   |
|----------------------|---|
| Squeegee Blade       | Stainless steel                                     |
| Squeegee Speed       | Capable of a max. printing speed of 150mm/sec       |
| Stencil Material     | Stainless steel                                     |
| Temperature/Humidity | Optimal conditions are 21-25°C and 35-65% humidity. |

**Cleaning:**

**BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN97C** is a no clean formulation- The residues left on the board are non-conductive and non corrosive and do not require removal in most applications. Although it is a no clean formulation, the residues can be easily removed with a variety of cleaning agents used in automated cleaning systems.

**Delivery sizes:**

Syringe/Cartridges: 5cc, 10cc, 30cc, 60cc, 120cc

**Storage and shelf life:**

It is recommended that **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN97C** is stored in clean dry conditions with temperature 5-10°C to maintain consistent reflow and print characteristics. **BALVER ZINN SOLDER PASTE RMA H-1 FDQ SN97C** should be equalized to room temperature prior to printing (minimum 8 hours). Do not use excessive heating. The time of storage in the original packaging at a temperature of 5 – 10°C amounts to 6 month in doses and 4 month in syringes or cartridges.

**Safety Advice**

Before use please refer to the appropriate Safety Data Sheet.

The information in this Data Sheet is based on data considered accurate. The measured values stated are based on own measurements, but do not represent assured properties or delivery specifications. Because of the vast number of different materials and applications – also with respect to possible protective rights of third parties – Balver Zinn Josef Jost GmbH & Co. KG **cannot** accept any liability.

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